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- Pin Transfer
- High Strength
- Low Thermal Resistance
- Electrically Conductive
- Epoxy Paste Adhesive
- IDEAL FOR:**
- Stamp or Pin Transfer Die Attach
- Conventional Die Attach
- Automated Assemblies
- Build-In Molecular Stress Relief
- Long Term Ambient Storage

DESCRIPTION:

ME8260-SLV-2 PART is a 2 part package version of ME8260-SLV for ease in shipping to outside of USA. When mix in 1/1 by weight ratio, it is a low viscosity and accelerated version of ME8260 for snap curing applications. This silver filled paste is solvent free, electrically and thermally conductive. It is designed for automated, online die attach processing.

ME8260-SLV is designed for die-attach with stress absorbing capability for sizes up to 2cm. The viscosity has been designed for stamp transfer dispensing of die-attach application.

AVAILABILITY:

ME8260-SLV-2 PART is available in jars of PART A and PART B of different sizes in equal weight.

APPLICATION PROCEDURES:

- (1) Thaw for 30 minutes before opening jar or using syringes.
- (2) Dispense adhesive onto clean substrate with a suitable pattern to assure full die coverage.
- (3) Cure according to one of the recommended cure schedules.

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details.
 The information contained herein is believed to be reliable. All recommendations or suggestions are made without guarantee inasmuch as conditions and methods of commercial use are beyond our control. Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is to be used in manufacturing and in the final product. Under no circumstance shall AI Technology be liable for accidental, consequential or other damages arising from the use or handling of this product.

While AI Technology owns all proprietary rights of material formulations of its products, specific usage in the manufacturing of certain products may involve patent rights of other companies.

PRIMA-SOLDER
ME8260-SLV-2 PART

TYPICAL PROPERTIES*

Electrical Resistivity (150 °C/ 60 minutes)	4×10^{-4} ohm-cm
Dielectric Strength (Volts/mil)	N/A
Glass Transition Temp.(°C)	80 ±10%
Current Carrying Capabilities	50 Amp/mm ²
Lap-Shear Strength	>1000 psi >6.9 N/mm ²
Device Push-off Strength	>2000 psi >13.8 N/mm ²
Hardness (Type)	80 (D) ±10%
Cured Density (gm/cc)	3.8 ±10%
Thermal Conductivity	>55 Btu-in/hr-ft ² -°F ±10% >7.9 W/m-°C ±10%
Linear Thermal Expansion Coeff. (ppm/°C)	40 ±15%
Maximum Continuous Operation Temp. (°C)	<150
Pot Life	2 days
Avg. Viscosity(5 rpm, 25°C) (Brookfield DV-1, Spindle CP51)	8,000 cp (TI~3.5) ±20%
Thixotropic Index	3.0 ±20%

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CURE SCHEDULES:

Temperature	Time	Pressure
125°C	>2 hr	
150°C	>30 min	

For higher temperature wire-bonding than 150°C, post-curing at the higher temperature is recommended.
 Pot-life after mixing is 5 days.

SHELF LIFE:

Storage temperature	Shelf Life
<40°C (Before mixing)	1 yr